#### 10/24/2023 508191278

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT8238463

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
JAY KUMAR SUNDARARAJAN	04/16/2018
RENQIU WANG	04/16/2018
HAO XU	04/11/2018
NAGA BHUSHAN	04/18/2018
HAITONG SUN	05/16/2018
WANSHI CHEN	04/11/2018

#### **RECEIVING PARTY DATA**

Name:	QUALCOMM INCORPORATED	
Street Address:	ss: 5775 MOREHOUSE DRIVE	
City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	18471277

## **CORRESPONDENCE DATA**

Fax Number: (303)473-2720

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3034732700

Email: brchristensen@hollandhart.com

HOLLAND & HART LLP/QUALCOMM **Correspondent Name:** 

Address Line 1: P.O. BOX 11583

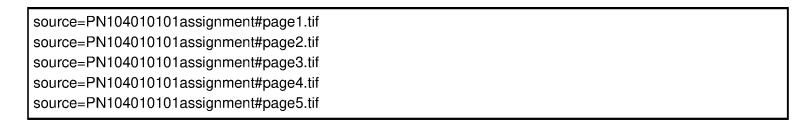
Address Line 4: SALT LAKE CITY, UTAH 84147

NAME OF SUBMITTER:  CHRISTOPHER M. SWICKHAMER  /Christopher M. Swickhamer/  DATE SIGNED:  10/24/2023	ATTORNEY DOCKET NUMBER:	PN104.01.01* (93519.3252)	
	NAME OF SUBMITTER:	CHRISTOPHER M. SWICKHAMER	
<b>DATE SIGNED:</b> 10/24/2023	SIGNATURE:	/Christopher M. Swickhamer/	
10/2 1/2029	DATE SIGNED:	10/24/2023	

**Total Attachments: 5** 

**PATENT** REEL: 065328 FRAME: 0787

508191278



#### ASSIGNMENT

#### WHEREAS, WE,

- 1. Jay Kumar SUNDARARAJAN, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, California, 92121-1714, and a resident of San Diego, California.
- 2. Renqiu WANG, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, California, 92121-1714, and a resident of San Diego, California,
- 3. Hao XU, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California, 92121-1714, and a resident of Beijing, China,
- 4. Naga BHUSHAN, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, California, 92121-1714, and a resident of San Diego, California.
- 5. Haitong SUN, a citizen of the People's Republic of China, having a mailing address located at 19319 Stevens Creek Boulevard, 94-DEF, Cupertino, California 95014, and a resident of Cupertino, California,
- 6. Wanshi CHEN, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, California, 92121-1714, and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to CODE BLOCK GROUPING AND FEEDBACK THAT SUPPORT EFFICIENT RETRANSMISSIONS (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, Qualcomm Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged. WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout

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the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 15/933,110 filed March 22, 2018, Qualcomm Reference No. 173274, and all provisional applications relating thereto, together with U.S. Provisional Application No. 62/476,673, filed March 24, 2017, Qualcomm Reference No. 173274P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance:

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	on Diego, CA on LOCATION	<u> April 16, 2018</u> DATE	Jay Kumár SUNDARARAJAN
Done at	ON VIEW , OR LOCATION	04/16/2218 DATE	Renqiu WANG
Done at	, on	DATE	Hao XU
Done at	SAN DIEGO, on LOCATION	4-(8-2018 DATE	Naga BHUSHAN
Done at_	LOCATION	DATE	Haitong SUN
Done at	LOCATION, OR	DATE	Wanshi CHEN

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at		, 68.	
	LOCATION	DATÉ	Jay Kumar SUNDARARAJAN
Done at	LOCATION	, on	Rengiu WANG
Done at &	kejji'ff Locknon	, 04/11/18/	Hão XII
Done at	LOCATION	, ONDATE:	Naga BHUSHAN
Done at	LOCATION	onDATE	Haitong SUN
Done at	LOCATION		Wanshi CHEN

PATENT QUALCOMM Ref. No. 173274 Page 3 of 3

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at		, on		
	LOCATION		DATE	Jay Kumar SUNDARARAJAN
Done at				Renqiu WANG
	LOCATION		DATE	Renqiu WANG
Done at		_, on		Hao XU
	LOCATION		DATE	Hao XU
Done at		on		Naga BHUSHAN
	LOCATION		DATE	Naga BHUSHAN
Done at	<u> </u>	on_	₹ijĠijĠ DATE	
	LDCATION		DATE	Haitong SUN
Done at			DATE	Wanshi CHEN
	T OCATION		DATE	Wanshi CHEN

**RECORDED: 10/24/2023**